Blakely, Sokoloff, Taylor & Zafman LLP (50 Title: Multi-Purpose Planarizing/Back-Grind/Pre-Underfill Arrangements for Bumped Wafers and Die 1st Named Inventor: Takashi Kumamoto Application No.: 09/893,588 Docket No.: 42 Sheet: 1 of 5 (503) 439-8778

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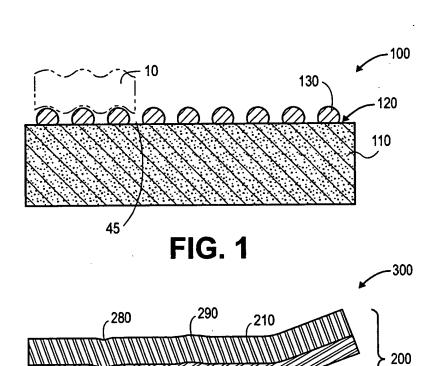


FIG. 2 300'

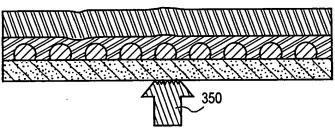
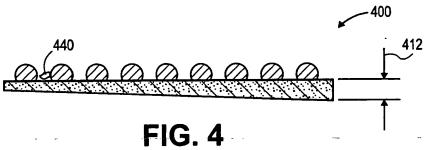


FIG. 3





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FIG. 5A

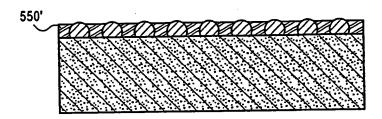


FIG. 5B

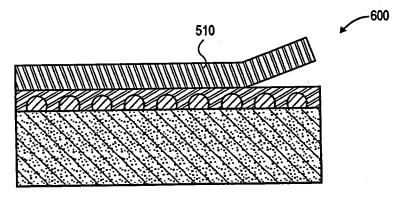


FIG. 6

-600'

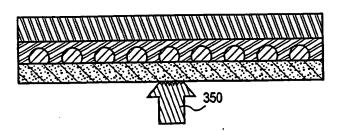
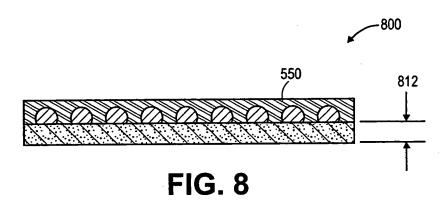


FIG. 7



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Docket No.: 42390P12093.



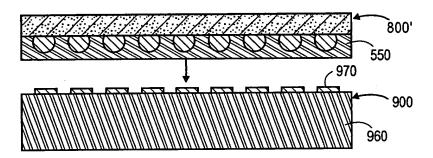


FIG. 9

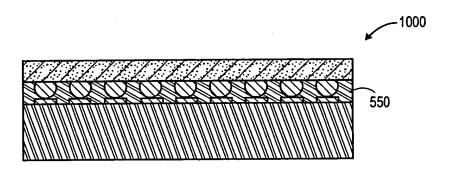


FIG. 10



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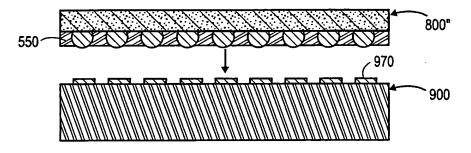


FIG. 11

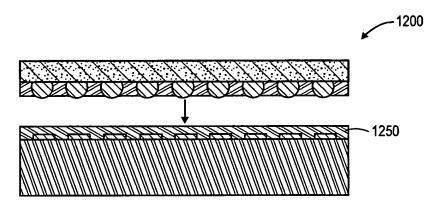


FIG. 12

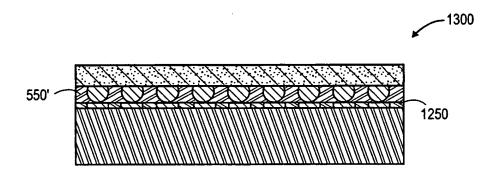
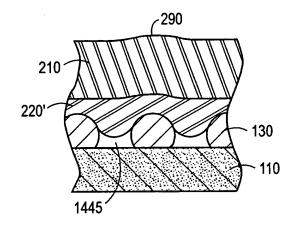


FIG. 13

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Docket No.: 42390P1209



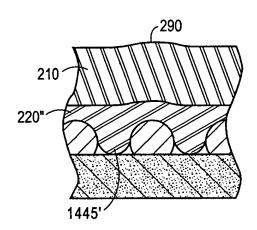


FIG. 14

FIG. 15